SEMICON® EUROPA

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Advanced Packaging Conference

R. Rettenmeier
Senior Product Marketing Manager
Evatec, Zurich, Switzerland

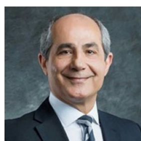
Biography

Roland Rettenmeier qualified as a Mechanical Engineer in 1997 and completed his MBA studies at Vienna, Austria in 2005. Roland extended his education through other international courses and programs since that time (e.g. Six Sigma Program with AT&S and Nokia; Innovation Technology Leader at Stanford University).

Roland has worked in the field of Electronics and Semiconductor manufacturing since 2001, managing multiple international projects. After joining Evatec in 2016 as Senior Product Marketing Manager (PMM) within the Business Unit for Advanced Packaging, he focused on business development for Panel Level Packaging where Evatec has now become the recognised market leader for thin film technology solutions. Since 2020 he has also supported development of Evatec's wafer level packaging solutions business.

In addition to his market and customer responsibilities, Roland represents Evatec in the Panel Level Packaging consortium of Fraunhofer IZM Berlin, in the Packaging Research Center at Georgia Tech, USA and in the Panel Level Packaging Consortium at the NCAP in Wuxi, China.

Welcome Remarks



L. Altimime
President
SEMI Europe, Berlin, Germany

Abstract

Coming Soon

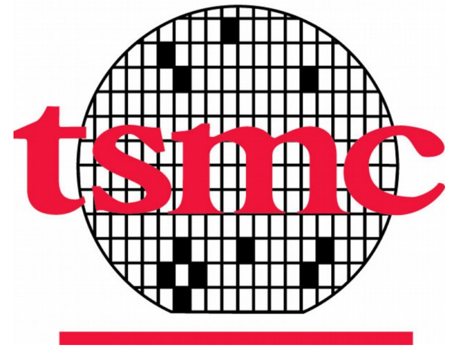
Biography

Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and

Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

Lights Outside Tunnel

D. Yu
Vice President of TSMC R&D and TSMC Distinguished Fellow
TSMC, Taipei City, Taiwan



Abstract
High Performance Compute (HPC) and AI/ML have been realized by advanced nodes IC and advanced system integration technologies. Device /chip scaling and heterogeneous system integration, eg. TSMC 3DFabric™, which consists of CoWoS®, InFO and SoIC®, become the twin engine to drive semiconductor technology. Recent new wave of generative AI with LLM showed that HPC and AI/ML have tremendous room for future growth. In the meantime, higher performance compute with higher energy efficiency become even more critical requirements than ever to support the demand. We will continue the scaling of both device/IC and advanced system in classical m-electronics based computing system. Furthermore, photonics-based system integration technology will be added which are complementary to the classical system integration to meet the ever-increasing energy efficient performance requirements for future HPC and AI/ML.

Biography
DDoug Yu is a Vice President of TSMC R&D and TSMC Distinguished Fellow, responsible for system integration technology pathfinding. Previously, Doug has pioneered and led TSMC Cu/Low-K technology development, industry first wafer-level system integration technology platform, TSMC 3DFabric™, including CoWoS®, InFO and SoIC™, and TSMC COUPE, a photonics-based system integration technology.
Prior to TSMC, Doug worked with AT&T Bell Labs. He received Ph.D. degree in Materials Science and Engineering from Georgia Institute of Technology, Atlanta, GA.
Doug is a recipient of IEEE Rao Tummala Award, IEEE EPS Microelectronics Manufacturing Award, and President Science Prize, Taiwan. He is an IEEE Fellow, TSMC Distinguished Fellow, and a member of National Academy of Engineering. He has given numerous invited/keynote/plenary speeches in international conferences and published 150+ papers to elevate system integration technology profile. He has (co)-authored 1500+ US granted semiconductor technology patents.

Latest Solutions in the Energy Efficiency of Electronic Systems

H. Voraberger
Corporate Vice President R&D
AT&S Austria Technologie & Systemtechnik
Aktiengesellschaft, Vienna, Austria

Abstract
Digitalization without further improvement in the energy efficiency of electronic systems will lead to a dramatic increase in energy requirements for data processing. The solution is based on processing systems with smaller nodes and a highly efficient power supply. Interconnect technology based on advanced IC substrate technologies offer great opportunities for improved signal processing and efficient power supply. Latest solutions will be presented in this talk.

Biography
Dr. Voraberger assumed his current position in 2010, as head of AT&S corporate research and development department. Previously Dr. Voraberger was responsible for AT&S corporate intellectual property and governmental funding.
He also established the R&D center in AT&S Shanghai (China) and was project leader for AT&S research and development in AT&S Leoben (Austria).
Dr. Voraberger studied industrial chemistry at Graz University of Technology, awarded multiple patents and has published several papers.